

M9061XX

Low Power MEMS Oscillator

Features

- Any Frequency Between 3.5 kHz and 100 MHz Accurate to 6 Decimal Places
- Low Power Consumption of 3.6 mA Typical
- CMOS-Compatible Output
- Industry-Standard Packages: 7.0 mm × 5.0 mm, 5.0 mm × 3.2 mm, 3.2 mm × 2.5 mm, 2.5 mm × 2.0 mm, 2.0 mm × 1.6 mm, 1.6 mm × 1.2 mm

Applications

- Low Power/Portable Instrumentation
- Military Systems
- Medical Equipment
- Communication Systems

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions	
Output Frequency	f _{OUT}	3.5k	—	100M	Hz	-	
		-20		+20		Inclusive of initial tolerance at +25°C and	
Frequency Stability	f _{STAB}	-25		+25	ppm	variations over operating temperature,	
		-50		+50		rated power supply voltage, and load.	
Aging	f	-5		+5	nnm	1st year at +25°C	
Aging	IAGING	-1		+1	ppm	After 1st year at +25°C	
On a matine Tanan and the		-20		+70			
Operating Temperature	T _{OP}	-40		+105	°C	—	
T ange		-40		+85			
		1.71	1.8	1.98			
		2.25	2.5	2.75			
Supply Voltage	V _{DD}	2.52	2.8	3.08	V	—	
		2.7	3.0	3.3			
		2.97	3.3	3.63			
		_	4.0	_	A	No load condition, f = 27 MHz, V _{DD} = 2.0V, 2.8V, 3.0V, or 3.3V	
Current Consumption	DD		3.0	_	1 MA	No load condition, f = 27 MHz, V_{DD} = 1.8V	
			1.5			V _{DD} = 2.0V or 3.3V	
Standby Current	I _{STD}		1	_	μA	V _{DD} = 1.8V, Output is Weakly Pulled Down	
Duty Cycle	DC	45	_	55	%	All supply voltage options	
Rise Time	t _r	_	0.6	1.3	ns	20% to 80% V_{DD} = 2.5V, 2.8V, 3.0V, or 3.3V; C _L = 10 pF	
Fall Time	t _f		1.3	2.0	ns	20% to 80% V_{DD} = 1.8V; C_{L} = 10 pF	
Output High Voltage	V _{OH}	80%			V _{DD}	I _{OH} = 3 mA	
Output Low Voltage	V _{OL}			20%	V _{DD}	$I_{OL} = -3 \text{ mA}$	
Input High Voltage	V _{IH}	70%			V _{DD}	Input logic high	
Input Low Voltage	V _{IL}			30%	V _{DD}	Input logic low	
Input Pull-Up Impedance	Z _{IN}		300		kΩ	Pin 1, OE logic high or logic low, or ST logic high	

PERFORMANCE SPECIFICATIONS

PERFORMANCE SPECIFICATIONS

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Start-Up Time	t _{START}	_	_	1.5	ms	From 90% V _{DD} to valid clock output, T = +25°C
Enable/Disable Time	t _{oe}	_	_	1	μs	Output disable time takes up to two periods of the output waveform + 200 ns
RMS Period Jitter	tjitt	_	7	_	ps	f = 27 MHz, V _{DD} = 2.5V, 2.8V, 3.0V, or 3.3V
	-	—	8.5	—		f = 27 MHz, V _{DD} = 1.8V
Cycle-to-Cycle Jitter	CCJIT	_	35	60	ps	f = 27 MHz, V _{DD} = 2.0V, 2.8V, 3.0V, or 3.3V
		_	50	70		f = 27 MHz, V _{DD} = 1.8V

ABSOLUTE MAXIMUM RATINGS

Parameter	Minimum	Maximum
Storage Temperature	–65°C	+150°C
V _{DD}	-0.5V	+4V
Electrostatic Discharge	_	2000V
Soldering Temperature (follow standard Pb-Free soldering guidelines)	_	+260°C

ENVIRONMENTAL COMPLIANCE

Parameter	Condition/Test Method		
Mechanical Shock	MIL-STD-883F, Method 2002		
Mechanical Vibration	MIL-STD-883F, Method 2007		
Temperature Cycle	JESD22, Method A104		
Solderability	MIL-STD-883F, Method 2003		
Moisture Sensitivity Level	MSL1 @ 260°C		

1.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 1-1.



TABLE 1-1:	PIN FUNCTION TABLE
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Pin Number	Pin Name	Description
		Output Enable or Active-Low Standby. H or Open*: Specified frequency output. L: Output is high impedance. Only output driver is disabled.
	OE/STBY	Standby. H or Open*: Specified frequency output. L: Output is low (weak pull down). Device goes to sleep mode. Supply current reduces to I _{STD} .
2	GND	Electrical ground power.
3	OUT	Oscillator output.
4	VDD	Power supply voltage.

2.0 FUNCTIONAL BLOCK DIAGRAM



3.0 RECOMMENDED REFLOW PROFILES FOR Pb-Free & Sn-Pb



FIGURE 3-1: Reflow Profile.

TABLE 3-1: REFLOW PROFILE

Profile Feature	Symbol	Sn-Pb Assembly	Pb-Free Assembly
Average Ramp-Up Rate	T _L to T _P	3°C/second max.	3°C/second max.
Pre-Heat Minimum Temperature	T _{S(MIN)}	135°C	150°C
Pre-Heat Maximum Temperature	T _{S(MAX)}	155°C	200°C
Pre-Heat Time (from min. to max.)	t _S	60 to 90 seconds	60 to 180 seconds
T _{S(MAX)} to T _L Ramp-Up Rate	—	3°C/second max.	3°C/second max.
Low Temperature of Critical Reflow Zone	ΤL	183°C	217°C
Time Maintained Above T _L	—	40 to 60 seconds	60 to 150 seconds
Peak Temperature	Τ _Ρ	230°C max.	260°C max.
Time from 25°C to Peak Temperature	—	4 minutes max.	8 minutes max.
Time within 5°C of Actual Peak Temperature	t _P	10 to 20 seconds max.	20 to 40 seconds max.
Ramp-Down Rate		6°C/second max.	6°C/second max.

Note: All temperatures refer to the topside of the package, measured on the package body surface.

4.0 PACKAGING INFORMATION

4.1 Package Marking Information



Note: If the full seven-character YYWWSSS code cannot fit on the package, the following truncated codes are used based on the available marking space:
6 Characters = YWWSSS; 5 Characters = WWSSS; 4 Characters = WSSS; 3 Characters = SS; 2 Characters = SS; 1 Character = S.

4-Lead Very Thin Dual Flatpack, No-Lead Package (JZA) - 7.0 mm × 5.0 mm Body [VDFN] with 2.2 mm × 3.5 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1025 Rev A Sheet 1 of 2

4-Lead Very Thin Dual Flatpack, No-Lead Package (JZA) - 7.0 mm × 5.0 mm Body [VDFN] with 2.2 mm × 3.5 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			S
Dimension	Limits	MIN	NOM	MAX
Number of Terminals	Ν		004	
Pitch	е		5.08 Ref	
Overall Height	А	0.80	0.85	0.90
Standoff	A1	0.00	-	0.05
Terminal Thickness	A3	0.203 Ref		
Overall Length	D	6.90	7.00	7.10
Exposed Pad Length	D2	2.10	2.20	2.30
Overall Width	E	4.90	5.00	5.10
Exposed Pad Width	E2	3.40	3.50	3.60
Terminal Width	b	1.35	1.40	1.45
Terminal Length	L	1.10	1.20	1.30

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the pin 1 area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1025 Rev A Sheet 2 of 2

4-Lead Very Thin Dual Flatpack, No-Lead Package (JZA) - 7.0 mm × 5.0 mm Body [VDFN] with 2.2 mm × 3.5 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

– SILK SCREEN

	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX
Optional Center Pad Width	X2			2.30
Optional Center Pad Length	Y2			3.60
Contact Pad Spacing	C1		5.08	
Contact Pad Spacing	C2		3.90	
Contact Pad Width (Xnn)	X1			1.50
Contact Pad Length (Xnn)	Y1			1.30
Contact Pad to Center Pad (Xnn)	G1	0.69		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

- 1. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- 2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3025 Rev A

4-Lead Very Thin Plastic Dual Flat, No-Lead Package (H6A) - 5.0 mm × 3.2 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1008 Rev A Sheet 1 of 2

4-Lead Very Thin Plastic Dual Flat, No-Lead Package (H6A) - 5.0 mm × 3.2 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			MILLIMETERS			
Dimensior	Limits	MIN	NOM	MAX			
Number of Terminals	Ν		4				
Pitch	е		2.54 BSC				
Overall Height	А	0.80	0.85	0.90			
Standoff	A1	0.00	0.02	0.05			
Terminal Thickness	A3	0.20 REF					
Overall Length	D	5.00 BSC					
Overall Width	E	3.20 BSC					
Terminal Width	b	1.15 1.20 1.25					
Terminal 1 Tab	b1	0.10 REF					
Terminal Length	L	0.80	0.90	1.00			
Terminal Pull Back	L1	0.10 REF					
Terminal 1 Tab	L2	0.20 REF					
Terminal 1 Chamfer	СН	0.25 REF					
Terminal Spacing	K		1.20 REF				

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1008 Rev A Sheet 2 of 2

4-Lead Very Thin Plastic Dual Flat, No-Lead Package (H6A) - 5.0 mm × 3.2 mm Body [VDFN]





RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E			
Contact Pad Spacing	С		2.00	
Contact Pad Width (X4)	X1			1.40
Contact Pad Width	X2			1.50
Contact Pad Length (X4)	Y1			1.10
Contact Pad Tab Length	Y2			0.36
Contact Pad to Center Pad (X2)	G1	1.00		
Contact Pad to Contact Pad (X2)	G2	1.14		
Terminal 1 Contact Pad Chamfer	CH		0.30	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3008 Rev A

4-Lead Very Thin Plastic Dual Flatpack No-Lead (H4A) - 3.2 mm × 2.5 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1006 Rev B Sheet 1 of 2

4-Lead Very Thin Plastic Dual Flatpack No-Lead (H4A) - 3.2 mm × 2.5 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX
Number of Terminals	N		4	
Pitch	е	2.10 BSC		
Overall Height	Α	0.80 0.85 0.90		
Standoff	A1	0.00	0.02	0.05
Overall Length	D	3.20 BSC		
Overall Width	E	2.50 BSC		
Terminal Width	b	0.85	0.90	0.95
Terminal Length	L	0.70	0.80	0.90
Terminal 1 Index Chamfer	СН	0.25 REF		

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1006 Rev B Sheet 2 of 2

4-Lead Very Thin Plastic Dual Flatpack No-Lead (H4A) - 3.2 mm × 2.5 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS					
Dimension Limits		MIN	NOM	MAX		
Contact Pitch	Contact Pitch E			2.10 BSC		
Contact Pad Spacing		1.80				
Contact Pad Width (Xnn)			0.90			
Contact Pad Length (Xnn)	Y			1.00		
Contact Pad Length (Xnn)		0.20 REF				

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-3006 Rev B

4-Lead Very Thin Land Grid Array (AUA) - 2.5 mm × 2.0 mm Body [VLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1202B Sheet 1 of 2

4-Lead Very Thin Land Grid Array (AUA) - 2.5 mm × 2.0 mm Body [VLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS					
Dimension	Limits	MIN	NOM	MAX		
Number of Terminals	Ν	4				
Terminal Pitch	е		1.65 BSC			
Terminal Pitch	e1	1.25 BSC				
Overall Height	Α	0.79 0.84 0.				
Standoff	A1	0.00	0.02	0.05		
Substrate Thickness (with Terminals)	A3	0.20 REF				
Overall Length	D	2.50 BSC				
Overall Width	Е	2.00 BSC				
Terminal Width	b1	0.60 0.65 0.70				
Terminal Length	L	0.60	0.65	0.70		
Terminal 1 Index Chamfer	СН	-	0.225	-		

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1202B Sheet 2 of 2

4-Lead Very Thin Land Grid Array (AUA) - 2.5 mm × 2.0 mm Body [VLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS				
Dimension	MIN	NOM	MAX		
Contact Pitch	E	1.65 BSC			
Contact Spacing	С		1.25		
Contact Width (X4)			0.70		
Contact Pad Length (X4)			0.80		
Space Between Contacts (X2)	G1	0.95			
Space Between Contacts (X2)	0.45				
Contact 1 Index Chamfer	0	.13 X 45° RE	F		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3202B

4-Lead Very Thin Fine Pitch Land Grid Array (ASA) - 2.0 mm × 1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1200 Rev D Sheet 1 of 2

4-Lead Very Thin Fine Pitch Land Grid Array (ASA) - 2.0 mm × 1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS					
Dimension	Dimension Limits					
Number of Terminals	Ν		4			
Terminal Pitch	е		1.55 BSC			
Terminal Pitch	e1	0.95 BSC				
Overall Height	Α	0.79 0.84 0.8				
Standoff	A1	0.00	0.02	0.05		
Substrate Thickness (with Terminals)	A3	0.20 REF				
Overall Length	D	2.00 BSC				
Overall Width	E	1.60 BSC				
Terminal Width	b1	0.30 0.35 0.40				
Terminal Width	0.40	0.45	0.50			
Terminal Length	0.50	0.55	0.60			
Terminal 1 Index Chamfer	CH	-	0.15	-		

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1200 Rev D Sheet 2 of 2

4-Lead Very Thin Fine Pitch Land Grid Array (ASA) - 2.0 mm × 1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS					
Dimensior	Dimension Limits					
Contact Pitch	Contact Pitch E			1.55 BSC		
Contact Spacing	С	0.95				
Contact Width	X1			0.50		
Contact Width (X3)	X2			0.40		
Contact Pad Length (X4)	Y			0.70		
Space Between Contacts	G1	1.05				
Space Between Contacts (X2)	G2	0.25				
Space Between Contacts	1.15					
Contact 1 Index Chamfer	СН	().13 X 45° RE	F		

Notes:

- 1. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- 2. The value in parenthesis, next to the item description is a unit multiplier.

Microchip Technology Drawing C04-3200 Rev D

4-Lead Very Thin Fine Pitch Land Grid Array (ARA) - 1.6 mm × 1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1199B Sheet 1 of 2

4-Lead Very Thin Fine Pitch Land Grid Array (ARA) - 1.6 mm × 1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS					
Dimension	Dimension Limits					
Number of Terminals	Ν		4			
Terminal Pitch	е		1.20 BSC			
Terminal Pitch	e1		0.75 BSC			
Overall Height	Α	0.79 0.84 0.8				
Standoff	A1	0.00	0.05			
Substrate Thickness (with Terminals)	0.20 REF					
Overall Length	D	1.60 BSC				
Overall Width	E		1.20 BSC			
Terminal Width	b1	0.25 0.30 0.3				
Terminal Width	0.325	0.375	0.425			
Terminal Length	L	0.30	0.35	0.40		
Terminal 1 Index Chamfer	СН	-	0.125	-		

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1199B Sheet 2 of 2

4-Lead Very Thin Fine Pitch Land Grid Array (ARA) - 1.6 mm × 1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E1	1.20 BSC		
Contact Pitch	E2			
Contact Spacing	С		0.75	
Contact Width (X3)	X1			0.35
Contact Width	X2			0.43
Contact Pad Length (X4)	Y			0.50
Space Between Contacts	G1	0.85		
Space Between Contacts (X2)	0.25			
Space Between Contacts	0.77			
Contact 1 Index Chamfer	0	.13 X 45° RE	F	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. The value in parenthesis, next to the item description is a unit multiplier.

Microchip Technology Drawing C04-3199B

APPENDIX A: REVISION HISTORY

Revision A (March 2023)

• Initial release of M9061xx as Microchip data sheet DS20006771A.

Revision B (February 2025)

- Updated temperature range options in the Product Identification System section and Performance Specifications table.
- Updated package labels on the Product Identification System page.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

xxxxx	X		X	X	X		X	X	- <u>xxx.xxxx</u> -xxxKxxx	[<u>X]</u> IX XXXXI
Device	Feature Pin	(Output Drive Strength	Package	Temperature R	ange 	Stability	Revision	Frequency	Media Type
Device:	M9061	=	Low Power MEMS O	scillator		Exa	mples:			
Feature Pir	n: 0 1	=	Enable/Disable Standby			a) N 125	1906101AE2E 0000	B- MS Pir 4-L Pa Ra B,	0061xx, Enable/Dis n, Standard Output Lead 1.6 mm × 1.2 ckage, –20°C to + nge, ±20 ppm Sta 125.0000 MHz Fre	sable Feature Drive Strength, mm VFLGA 70°C Temp. bility, Revision equency, Cut
Drive Strength:	1	=	Standard			b) N 024	1906111CI1B .0000	- M9 Sta	pe/non-TR 0061xx, Standby F andard Output Driv ad 7.0 mm x 5.0 m	eature Pin, ve Strength, 4-
Package:	A B C J M	= = =	4-Lead 7.0 mm × 5.0 4-Lead 5.0 mm × 3.2 4-Lead 3.2 mm × 2.5 4-Lead 2.0 mm × 1.0 4-Lead 1.6 mm × 1.2	mm VDFN mm VDFN mm VDFN mm VLGA mm VFLGA		c) M	1906101CE2F	ag ±2 02 Taj 3- MS	e, –40°C to +105°(5 ppm Stability, Re 4.0000 MHz Frequ pe/non-TR	c Temp. Range, evision B, lency, Cut
Temperatu Range:	re L E	= = =	-40°C to +105°C -40°C to +85°C -20°C to +70°C	mm vflga		026	0000	Pir 4-L Pa Ra B, Ta	n, Standard Output ead 5.0 mm × 3.2 ckage, –40°C to + nge, ±50 ppm Sta 026.0000 MHz Fre pe/non-TR	Drive Strength, mm VDFN 85°C Temp. bility, Revision equency, Cut
Stability: Revision:	1 2 3 B	= = =	±50 ppm ±25 ppm ±20 ppm Revision B			d) M 033	1906111JI1B- 3333	MS Sta Le ag ±2 03 Ta	0061xx, Standby F andard Output Driv ad 3.2 mm × 2.5 n e, -20°C to +70°C 0 ppm Stability, Re 3.3333 MHz Frequ be/non-TR	eature Pin, /e Strength, 4- nm VDFN Pack- Temp. Range, evision B, iency, Cut
Frequency	xxx.xxxx xxxKxxx	=	User-Defined Frequei and 100.0 User-Defined Frequei and 999.9	ncy Between 0 000 MHz ncy Between 0 99 kHz	001.0000 MHz 003.500 kHz	e) N 025	1906101ME2 0000	B- MS Pir 4-L Pa Ra B, Ta	0061xx, Enable/Dis n, Standard Output ead 2.5 mm × 2.0 ckage, –20°C to + nge, ±25 ppm Sta 025.0000 MHz Fre pe/non-TR	sable Feature Drive Strength, mm VLGA 70°C Temp. bility, Revision equency, Cut
Media Type	<blank> : T T_SNPB See the N</blank>	= = = Minir	Cut Tape/non-TR qua Tape and Reel Tin Lead (SnPb) Sold mum Order Quantity tab	ntities er Dip Ie for more inf	ormation.	f) M906111HI1B- 100K000 Standard Output Drive S Lead 2.0 mm × 1.6 mm \ Package, -40°C to +105 Range, ±20 ppm Stability		eature Pin, ve Strength, 4- nm VFLGA 105°C Temp. bility, Revision		
Note 1: 2:	The SnPb s (4-Lead 1.6 Tape and R description. printed on t Office for p	solde mr teel Thi he c acka	er dip media type is not n × 1.2 mm VFLGA). identifier only appears i is identifier is used for o levice package. Check age availability with the	supported for n the catalog p rdering purpos with your Micro Tape and Reel	Package H bart number ses and is not ochip Sales l option.	g) M 026 h) M 050	1906101AE28 0000T 1906111C11B 0000T_SNPI	- MS - MS - MS - Pir 4-L Pa - Ra B, an - MS - MS - MS - 4-I	be/non-TR 0061xx, Enable/Dis n, Standard Output .ead 1.6 mm × 1.2 ckage, -20°C to + nge, ±20 ppm Sta 026.0000 MHz Fre d Reel 0061xx, Enable/Dis n, Standard Output .ead 3.2 mm × 2.5	sable Feature Drive Strength, mm VFLGA 70°C Temp. bility, Revision equency, Tape sable Feature Drive Strength, mm VFI GA
								Pa Ra B, Le	ckage, –40°C to + nge, ±20 ppm Sta 050.0000 MHz Fre ad Solder Dip	85°C Temp. bility, Revision equency, Tin

MINIMUM ORDER QUANTITY

Package or Media Type	Pieces	Notes
Package A	50 pieces per tube	100 piece minimum order
Package B	72 pieces per tube	144 piece minimum order
Package C	110 pieces per tube	_
Package J	140 pieces per tube	_
Package M	100 pieces per bag	
Package H	100 pieces per bag	_
Tape and Reel	1000 pieces per reel	_
SnPb Solder Dip	500 pieces per reel	

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